

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

DAE
#5

In re Application of: Yuen, et al	Group Art Unit: 1765
Serial No: 09/718,319	Examiner: Unknown
Confirmation No: 3056	Attorney Docket No: 004704 USA/ETCH/SILICON/JB
Filed: 21 November 2000	November 2, 2001 San Francisco, California
For: ETCHING A SUBSTRATE IN A PROCESS ZONE	

Petition Under 37 C.F.R. 1.10(c)

Office of Petitions
Commissioner for Patents
Washington, D.C. 20231

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Dear Sir:

This petition is in response to the "Response to Request Corrected Filing Receipt" dated September 17, 2001.

This is a petition to amend the filing date of the instant application and to accord the correspondence in the above-identified application the "date-in" of November 21, 2000 as shown by the United States Post Office stamp bearing the same date on the Express Mail label no. EL356915802US. It is respectfully contended that the date of November 22, 2000 accorded this correspondence by the PTO is incorrect.

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to:

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By Rowena Montoya Dated 2 November 2001
Rowena Montoya

S/N: 09/718,319
Page 2 of 2

Enclosed is a true copy of the original Express mail label and the first page of the patent specification which contains an express mail label under the specifications of §1.10(a).

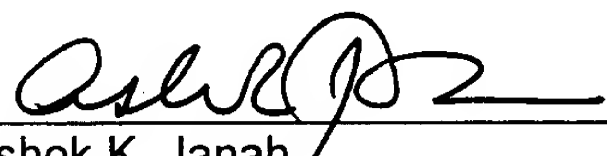
Applicant respectfully requests that the Patent Office correct the Filing Receipt accordingly and forward a corrected copy to the Applicant.

It is believed that no fee is due for the filing of this petition. However, if any fee is due, please charge it to deposit account number 10-0258.

Respectfully submitted,

JANAH & ASSOCIATES
A PROFESSIONAL CORPORATION

Date: 11/2/01

By: 
Ashok K. Janah
Reg. No. 37,487

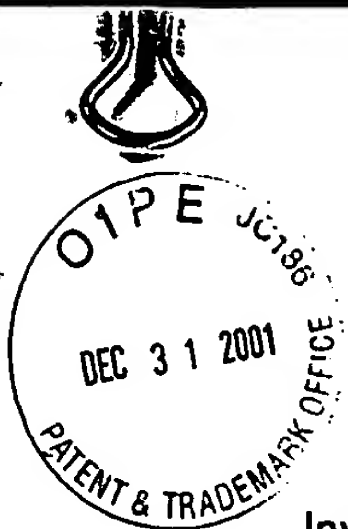
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Enclosures



United States Patent Application for:

ETCHING A SUBSTRATE IN A PROCESS ZONE

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Assignee: Applied Materials, Inc.

Entity: Large Entity

Docket No.: 4704/USA/ETCH/SILICON

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By BETH MULCAHY

Signature Beth Mulcahy